	1	2	3	4	5	6
	·		5	~	•	
A						A
				575-8 VinGnd	575-8 VoutGnd	
				VinGnd	VoutGnd	
		575-8 JVin O			and	
в	sw Vi	in = 3.5 V to 42 V	2.2µF 20 PVIN SW 3	8.2µH Rbias Rbode		в
	sw		anable do		GND	
		CIO1 CIO2 CIO3 CIN2 CIN2 CIN2 CIN2 CIN2 CIN2 CIN2 CIN2	12CIN1 CBOOD 6 T150µF Pgood 16 PGOOD BIAS 9		COUT5 COUT6 470pF 470pF 470pF	
				\$100k	470pF 470pF	
				Feedback		
	GndOut Gnd Cntr0	Gnd EnGnd SyncGnd SwGnd Pgood	SYIL 7 AGND 13   19 NC AGND 14   19 NC AGND 14   20 NC AGND 14   20 NC AGND 14   20 NC PGND 24   20 NC PGND 24   20 NC PGND 24   20 NC PGND 24   20 NC PGND 24	DNP Rfb Cbias 1µF		
	gnd gnd gn	Snd EnGnd SyncGnd SwGnd Pgood d gnd gnd gnd Pgood	27 NC PGND 24   28 NC PGND 25   29 NC PGND 26   20 NC PGND 26   DNP 30 NC PGND 27			
			Css PAD 31 10pF LM76003RNPR	<u>+</u>	Veg Vout Vout = -5 V to -15 V	
			L	vo vos		
с	Pt			Net-Tie ZXMP6A	JVout1 575-8	с
		MMBT3906 Rctrl 2 Qctrl 3 Feedback	MMBT3906 REsync 2 Qsync 3	Qen enableQ 3	2 REen	
	DNP Rt 82.5k		Sync 6.98k Cspeedup - syncQ	RCen 4.99k	6.98k En	
			100pF GND		Vin Line	gnd
	Neg Vout	GND	GND Neg Vout	Neg Vout 🚍 GND	Rpullup ≹10.0k	DNP \$4.99k
		GNU	Sync 3	ncQ sync	enableQ enable	Pgood RPGb \$10.0k
			800-10-003-10-001000	Neg Vout		Neg Vout
				800-10-003-10-001000		
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